



PowerPAK[®] 10 x 12 + Gen 4 600 V Superjunction MOSFETs With Fast Body Diode

INDUSTRY'S LOWEST $R_{DS(ON)} \times Q_g$ FOM

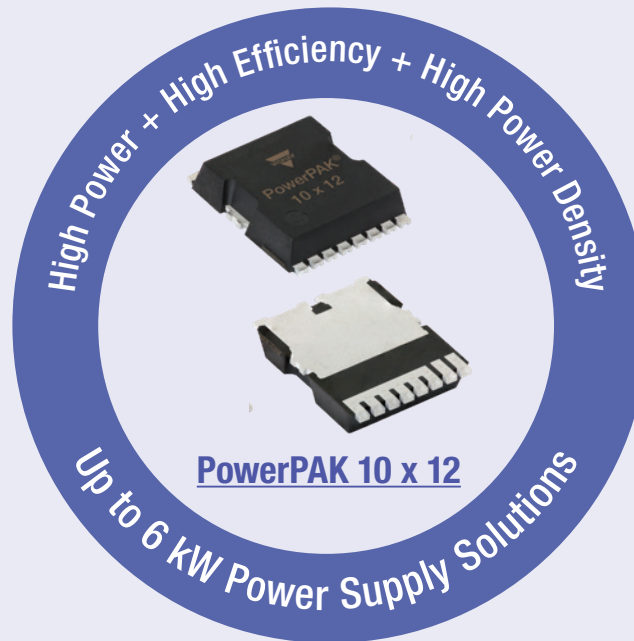
- Boosts system efficiency
- Addresses titanium efficiency requirement
- Enables higher power rating and power density
- High I_D current capability

BEST THERMAL CAPABILITY OF ANY SURFACE-MOUNT PACKAGE

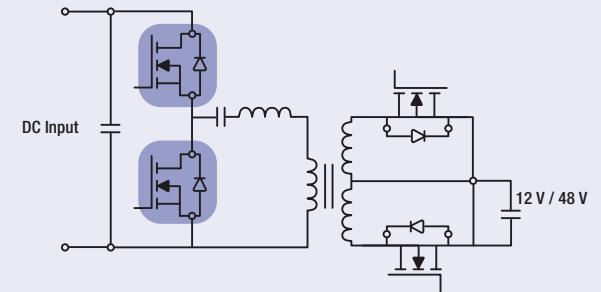
- Low profile, dimensions:
9.9 mm x 11.7 mm x 2.3 mm
- TO leadless package
- Integrated Kelvin source connection

LOW $C_{o(tr)}$ + LOW Q_{rr} + LOW Q_g

- Together enable "perfect LLC"



LLC RESONANT CONVERTER CIRCUIT DIAGRAM



Gen 4 600 V superjunction MOSFETs in the PowerPAK 10 x 12 package enable a 10x reduction of Q_{rr} to avoid hard commutation in bridge technologies and a 2x reduction of $C_{o(tr)}$ in charging / discharging time over competition to achieve ZVS.

APPLICATIONS



TELECOM



SOLAR /
PV INVERTER



UPS



GAMING PC



SERVERS /
DATACENTERS

3-PHASE LLC AT 5.2 kW TELECOM POWER SUPPLY

